

ABSTRACT OF THE DISCLOSURE

A thermal interface material is described for thermal coupling of an electronic component to a thermally conductive member. The thermal interface material includes a viscoelastic polymer matrix material, fusible solder particles in the matrix material, and filler particles in the matrix material. The solder particles have a melting temperature below a selected temperature (e.g. 157°C for indium) and the filler particles have a melting temperature substantially above the selected temperature (e.g. 961°C for silver). The filler particles keep the thermal interface material intact under adverse thermal and stress conditions.

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